The IEEE International Symposium on Circuits and Systems (ISCAS) is the flagship conference of the IEEE Circuits and Systems Society and the world’s premier forum for researchers in the active fields of theory, design and implementation of circuits and systems. ISCAS typically attracts 1000+ attendees from academia, research & industry spread across the globe in the fields of theory, design, and implementation of Circuits & Systems. The theme of ISCAS 2024 is **Circuits and Systems for Sustainable Development** and will be held in Singapore, from May 19 to 22, 2024. This symposium will include technical oral lectures and poster sessions, special sessions, tutorials, live demos and workshops highlighting the following innovation themes:

- Artificial Intelligence and Deep Learning
- Smart Systems for Automotive
- Brain: Innovation Neurotechnologies
- Intelligent Cyber Security Systems
- Food Security and Climate Change
- Ultra Low Power Circuits and Systems

IEEE ISCAS 2024’s organizing committee has created a set of sponsorship opportunity packages to provide the best possible **Return on Investment** for your business: **Gold**, **Platinum**, and **Diamond**. For more information, please contact our Sponsorship/Exhibition Co-Chairs: Xuanyao Fong (kelvin.xy.fong@nus.edu.sg), Anh Tuan Do (doat@ime.a-star.edu.sg), Zhengguo Li (ezgli@i2r.a-star.edu.sg).

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<td>Complementary registration to industry program, gala dinner and tutorial</td>
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<tr>
<td>One exhibition booth</td>
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<td>One-minute company video before plenary</td>
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<td>Access to a meeting room (interviews, hospitality) - reservation needed</td>
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* Customized package can be discussed upon request.

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